

Power MOSFET

TO-220AB


N-Channel MOSFET

FEATURES

- Low gate charge Q_g results in simple drive requirement
- Improved gate, avalanche, and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Effective C_{oss} specified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS*
Available

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptable power supply
- High speed power switching

TYPICAL SMPS TOPOLOGIES

- Single transistor flyback Xfmr. reset
- Single transistor forward Xfmr. reset (both for US line input only)

PRODUCT SUMMARY

V_{DS} (V)	400	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V	0.55
Q_g (Max.) (nC)	36	
Q_{gs} (nC)	9.9	
Q_{gd} (nC)	16	
Configuration	Single	

ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	IRF740APbF
Lead (Pb)-free and halogen-free	IRF740APbF-BE3


ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V_{DS}	400	V	
Gate-source voltage	V_{GS}	± 30		
Continuous drain current	V_{GS} at 10 V	$T_C = 25$ °C	10	A
		$T_C = 100$ °C	6.3	
Pulsed drain current ^a	I_{DM}	40		
Linear derating factor		1.0	W/°C	
Single pulse avalanche energy ^b	E_{AS}	630	mJ	
Repetitive avalanche current ^a	I_{AR}	10	A	
Repetitive avalanche energy ^a	E_{AR}	12.5	mJ	
Maximum power dissipation	$T_C = 25$ °C	P_D	125	W
Peak diode recovery dV/dt ^c		dV/dt	5.9	V/ns
Operating junction and storage temperature range	T_J, T_{stg}		- 55 to + 150	°C
Soldering recommendations (peak temperature) ^d	For 10 s		300 ^d	
Mounting torque	6-32 or M3 screw		10	
			1.1	N · m

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 12.6$ mH, $R_g = 25$ Ω , $I_{AS} = 10$ A (see fig. 12)
- $I_{SD} \leq 10$ A, $dV/dt \leq 330$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C
- 1.6 mm from case

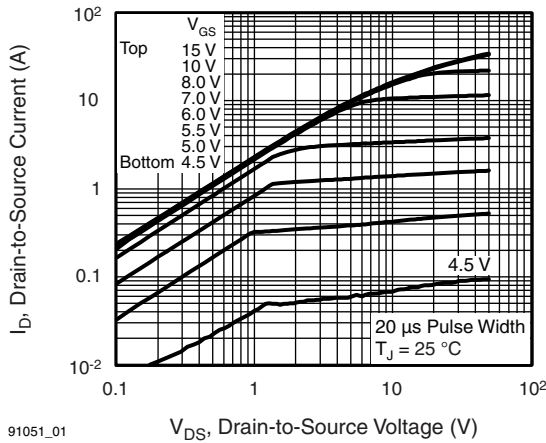
THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Case-to-sink, flat, greased surface	R_{thCS}	0.50	-	
Maximum junction-to-case (drain)	R_{thJC}	-	1.0	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		400	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.48	-	V/°C
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$		-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA
		$V_{DS} = 320\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 6.0\text{ A}^b$	-	-	0.55	Ω
Forward transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 6.0\text{ A}^b$		4.9	-	-	S
Dynamic							
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5		-	1030	-	μF
Output capacitance	C_{oss}			-	170	-	
Reverse transfer capacitance	C_{rss}			-	7.7	-	
Output capacitance	C_{oss}	$V_{GS} = 0\text{ V}, V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$		-	1490	-	μF
		$V_{GS} = 0\text{ V}, V_{DS} = 320\text{ V}, f = 1.0\text{ MHz}$		-	52	-	
Effective output capacitance	C_{oss}	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 320\text{ V}$		-	61	-	μF
Total gate charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}, V_{DS} = 320\text{ V}$, see fig. 6 and 13 ^b	-	-	36	nC
Gate-source charge	Q_{gs}			-	-	9.9	
Gate-drain charge	Q_{gd}			-	-	16	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 200\text{ V}, I_D = 10\text{ A}, R_g = 10\text{ }\Omega, R_D = 19.5\text{ }\Omega$, see fig. 10 ^b		-	10	-	ns
Rise time	t_r			-	35	-	
Turn-off delay time	$t_{d(off)}$			-	24	-	
Fall time	t_f			-	22	-	
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	10	A
Pulsed diode forward current ^a	I_{SM}			-	-	40	
Body diode voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 10\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	2.0	V
Body diode reverse recovery time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 10\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$		-	240	360	ns
Body diode reverse recovery charge	Q_{rr}			-	1.9	2.9	μC
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

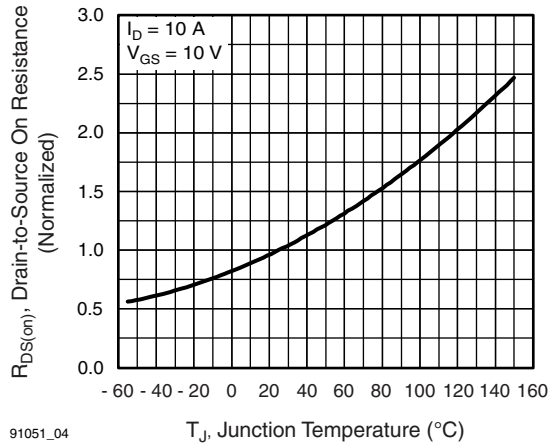
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
 b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



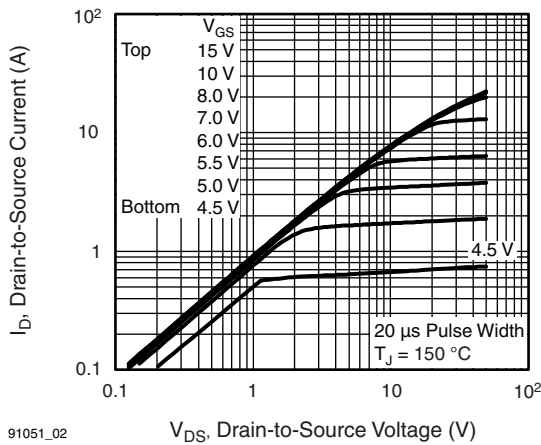
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Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$



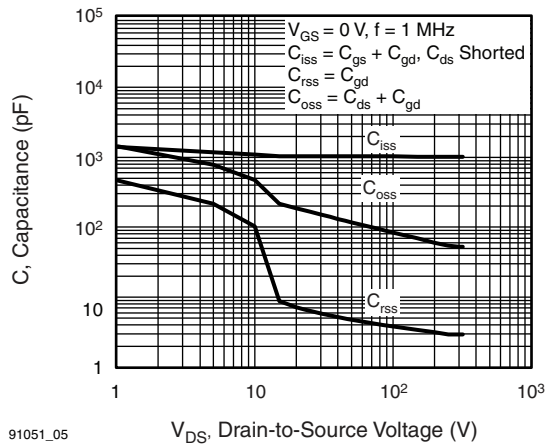
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Fig. 3 - Normalized On-Resistance vs. Temperature



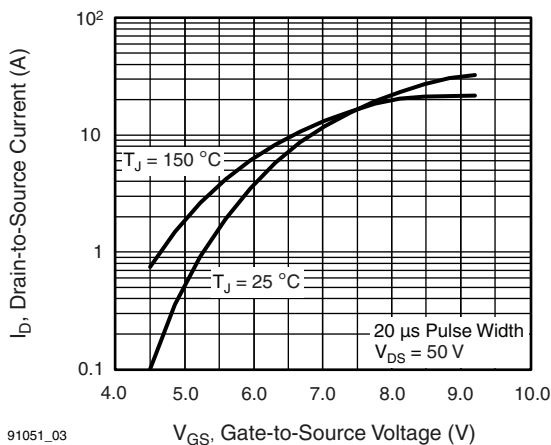
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Fig. 1 - Typical Output Characteristics, $T_C = 150\text{ }^\circ\text{C}$



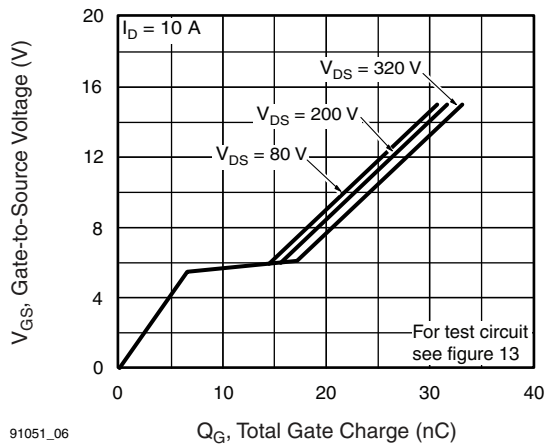
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Fig. 4 - Typical Capacitance vs. Drain-to-Source Voltage



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Fig. 2 - Typical Transfer Characteristics



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Fig. 5 - Typical Gate Charge vs. Gate-to-Source Voltage

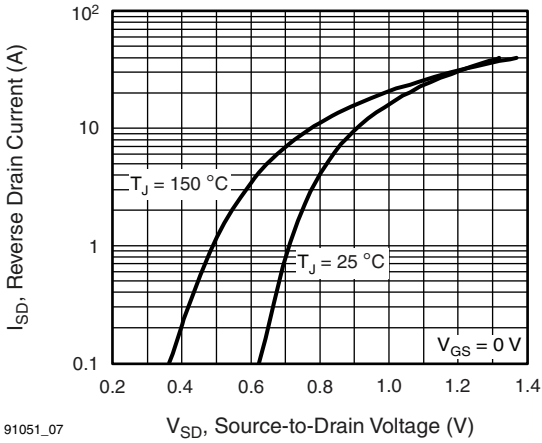


Fig. 6 - Typical Source-Drain Diode Forward Voltage

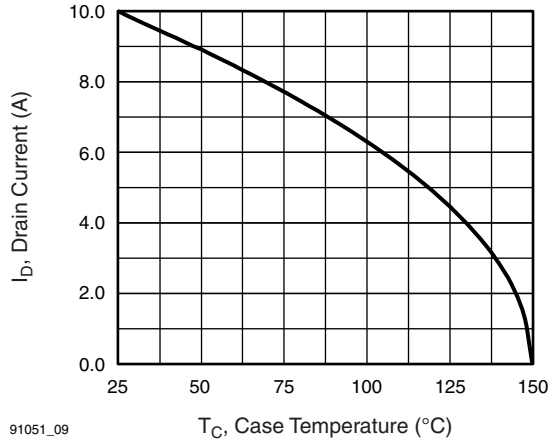


Fig. 8 - Maximum Drain Current vs. Case Temperature

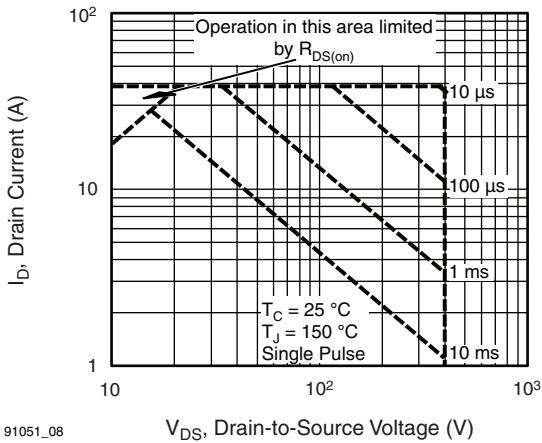


Fig. 7 - Maximum Safe Operating Area

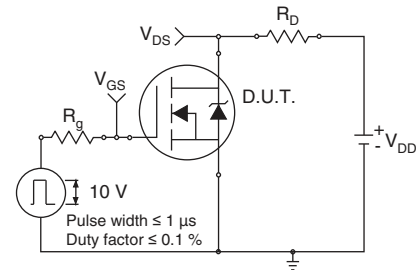


Fig. 9 - Switching Time Test Circuit

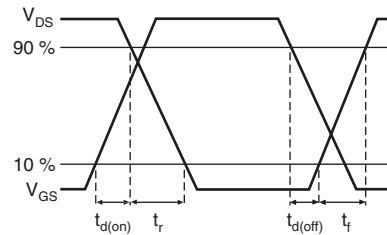
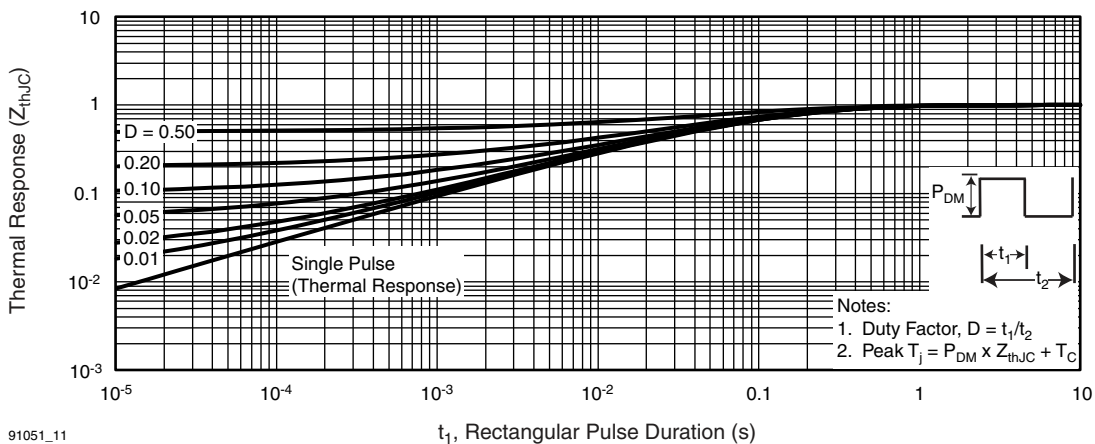


Fig. 10 - Switching Time Waveforms



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Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

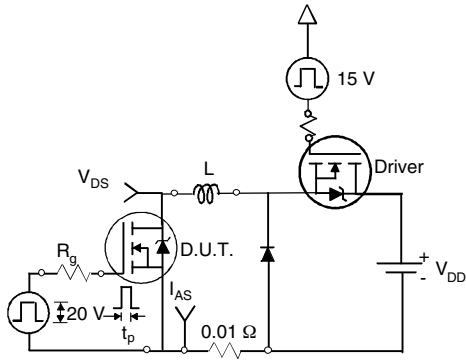


Fig. 12 - Unclamped Inductive Test Circuit

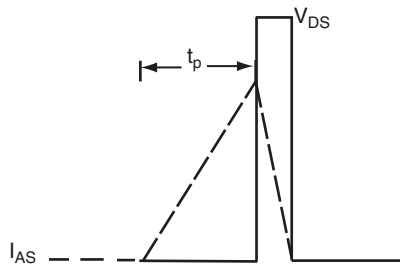
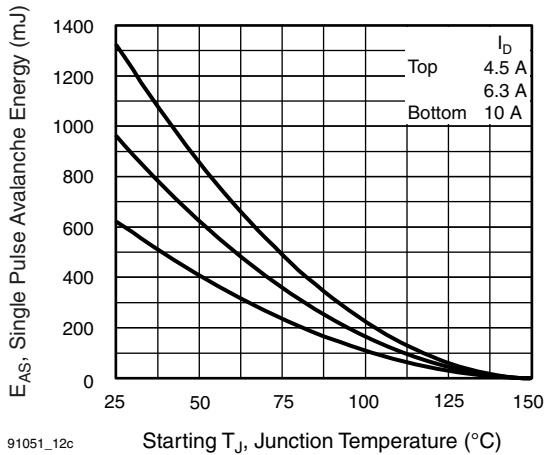
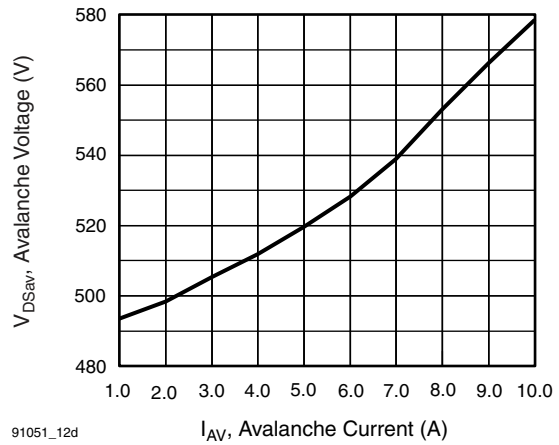


Fig. 13 - Unclamped Inductive Waveforms



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Fig. 14 - Maximum Avalanche Energy vs. Drain Current



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Fig. 15 - Typical Drain-to-Source Voltage vs. Avalanche Current

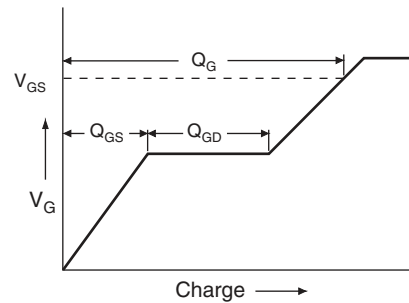


Fig. 16 - Basic Gate Charge Waveform

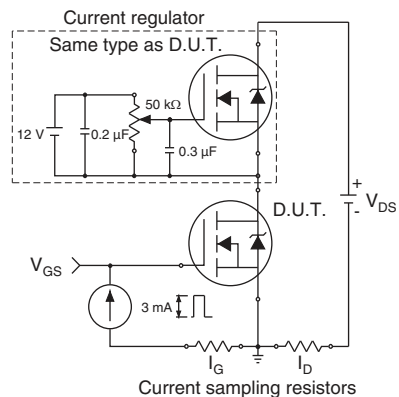
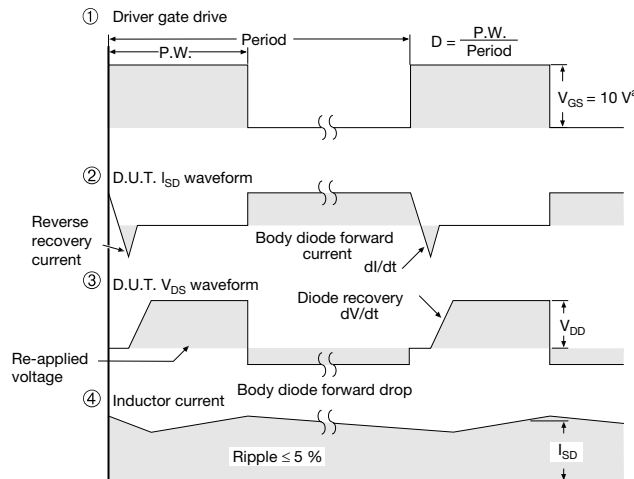
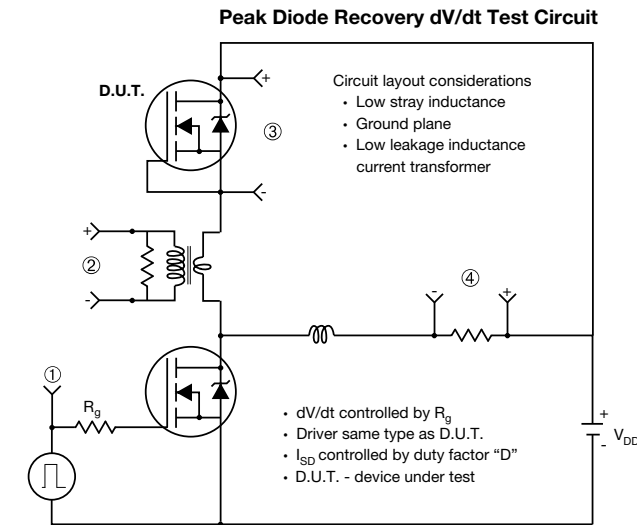


Fig. 17 - Gate Charge Test Circuit



Note
a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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